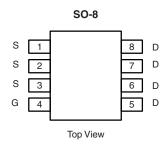




N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)		
30	0.0094 at V _{GS} = 10 V	16	14 nC		
	0.0115 at V _{GS} = 4.5 V	14	14110		



Ordering Information: Si4684DY-T1-E3 (Lead (Pb)-free)

Si4684DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

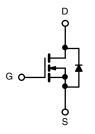
- Halogen-free According to IEC 61249-2-21 Definition
- Extremely Low Q_{gd} for Low Switching Losses TrenchFET $^{@}$ Power MOSFET
- 100 % R_q Tested
- Compliant to RoHS Directive 2002/95/EC



COMPLIANT HALOGEN FREE

APPLICATIONS

- High-Side DC/DC Conversion
 - Notebook
 - Server



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	S (T _A = 25 °C, unle	ss otherwise no	ted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage	V _{GS}	± 12			
	T _C = 25 °C		16		
Continuous Dusin Commant (T., 150 °C)	T _C = 70 °C		12.9		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	12 ^{b, c}		
	T _A = 70 °C		9.5 ^{b, c}	_ ,	
Pulsed Drain Current		I _{DM}	50	A	
Continuous Courses Brain Binds Coursest	T _C = 25 °C		4.0	\neg	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.3 ^{b, c}		
Single Pulse Avalanche Current	. 0.411	I _{AS}	20		
Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ	
	T _C = 25 °C		4.45		
Maximum Davian Dissipation	T _C = 70 °C	_	2.85	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.50 ^{b, c}		
	T _A = 70 °C		1.6 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	36	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{th IF}	22	28	- C/VV	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 90 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I - 250 uA		30		\/\0C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	ID = 200 UA		4.5		mV/°C	
Cata Carrea Threathald Valtage	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.6		1.5	V	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 5 \text{ mA}$		1.1			
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	1	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА	
	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
Drain-Source On-State Resistance ^a	В	$V_{GS} = 10 \text{ V}, I_D = 16 \text{ A}$		0.0078	0.0094	Ω	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 9.5 \text{ A}$		0.0092	0.0115		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 16 \text{ A}$		45		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2080			
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		340		pF	
Reverse Transfer Capacitance	C _{rss}			135			
Tatal Cata Chausa	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 11 A		30	45	nC	
Total Gate Charge				14	21		
Gate-Source Charge		$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 11 \text{ A}$		3			
Gate-Drain Charge	Q_{gd}			2.8			
Gate Resistance	R _q	f = 1 MHz	0.2	0.55	0.9	Ω	
Turn-On Delay Time	t _{d(on)}			15	25		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_1 = 1.87 \Omega$		60	100	<u> </u>	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		28	45		
Fall Time	t _f			9	15		
Turn-On Delay Time	t _{d(on)}			12	20	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V, R}_{1} = 1.87 \Omega$		12	20	- - -	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 8 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		45	70		
Fall Time	t _f			11	18		
Drain-Source Body Diode Characterist	•						
Continuous Source-Drain Diode Current	Is	T _C = 25 °C			4		
Pulse Diode Forward Current ^a	I _{SM}				50	Α	
Body Diode Voltage	V _{SD}	I _S = 2.3 A		0.70	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}	,		30	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			26	40	nC	
Reverse Recovery Fall Time	t _a	$I_F = 9.5 \text{ A, dl/dt} = 100 \text{ A/µs, T}_J = 25 ^{\circ}\text{C}$		16			
Reverse Recovery Rise Time	t _b			14		ns	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

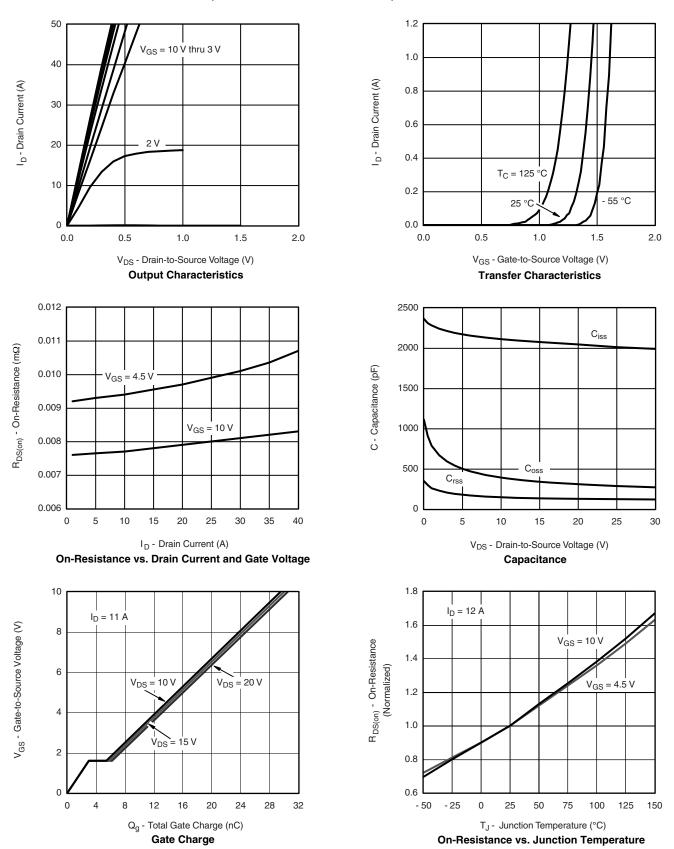
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.



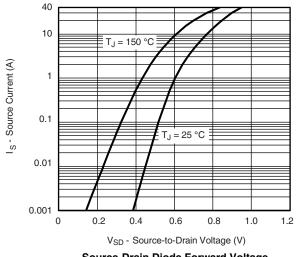


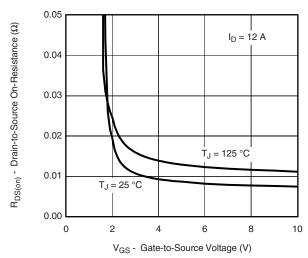
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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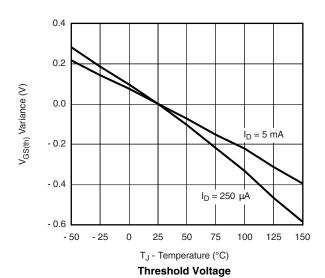
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

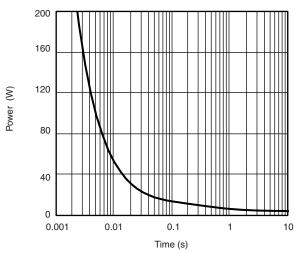




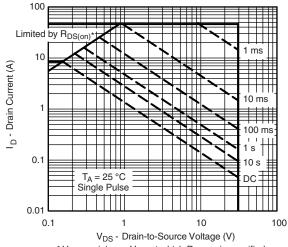
Source-Drain Diode Forward Voltage







Single Pulse Power, Junction-to-Ambient



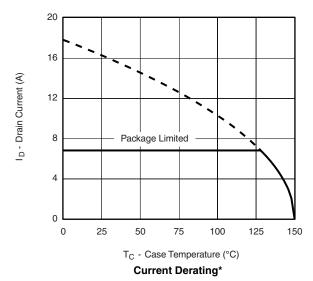
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified Safe Operating Area, Junction-to-Ambient

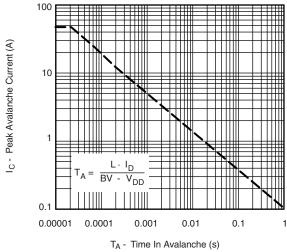






TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





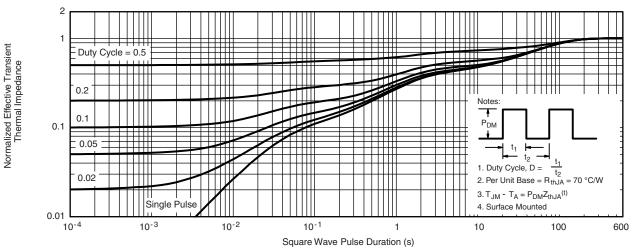
Single Pulse Avalanche Capability

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

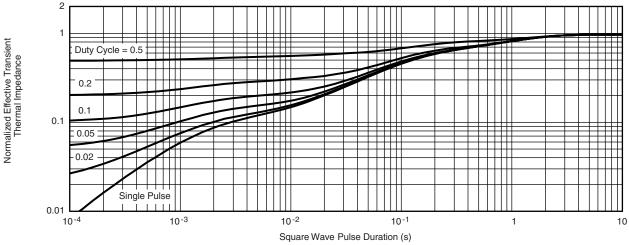
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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